

IN THE CLAIMS

Claim 1 (**currently amended**). ~~An~~ **A heat-activable** adhesive sheet of an adhesive system composed of a thermoplastic and optionally one or more resins, having

- a) a softening temperature of greater than 65°C and less than 125°C,
- b) a melt flow index (ISO 1133) of greater than 3 and less than 100 cm³/10 minutes,
- c) a storage modulus G' at 23°C, as measured by test method A, of greater than 10⁷ Pas,
- d) a loss modulus G'' at 23°C, as measured by test method A, of greater than 10⁶ Pas,
- e) and a crossover, as measured by test method A, of less than 125°C.

Claim 2 (**currently amended**). The **heat-activable** adhesive sheet of claim 1, wherein the layer thickness is between 10 and 100 µm.

Claim 3 (**currently amended**). The **heat-activable** adhesive sheet of claim 1, wherein said thermoplastic is selected from the group consisting of copolyamides, polyethyl-vinyl acetates, polyvinyl acetates, polyolefins, polyurethanes, and copolyesters.

Claim 4 (**currently amended**). The **heat-activable** adhesive sheet of claim 1, wherein said resins are reactive resins comprising one or more members of the group consisting of epoxy resins, phenolic resins and novolak resins.

Claim 5 (**currently amended**). A method for bonding chip modules in card bodies which comprises bonding said chip modules in said card bodies with the **heat-activable** adhesive sheet of claim 1.

Claim 6 (previously presented). The method of claim 5, wherein said chip modules are polyimide-, polyester or epoxy-based chip modules and said card bodies are PVC, ABS, PET, PC, PP or PE card bodies.

Claim 7 (previously presented). A method for producing a heat-activable adhesive tape, which comprises coating an adhesive system composed of a thermoplastic and optionally one or more resins, having

- a) a softening temperature of greater than 65 °C and less than 125 °C,
- b) a melt flow index (ISO 1133) of greater than 3 and less than 100 cm³/10 minutes,
- f) a storage modulus G' at 23 °C, as measured by test method A, of greater than 10⁷ Pas,
- g) a loss modulus G'' at 23 °C, as measured by test method A, of greater than 10⁶ Pas,
- h) and a crossover, as measured by test method A, of less than 125 °C

onto a release paper or a release film.

Claim 8 (previously presented). The adhesive sheet of claim 2, wherein said layer thickness is between 30 and 80 µm.